IPC - ASSOCIATION CONNECTINI- ELECTRONICS INDUSTRIES	© Copyright 2005. IPC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both nternational and Pan-American copyright conventions.			der both le	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1					Form Type * Distribute	* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi				ials and Mfg Information				
upplier Inform	ation													
Company name*			Company unique ID			τ	Unique ID Authority				Response Date*			
nsemi											2025-06-04			
Contact Name		Title - Contact			P	Phone - Contact*				Email - Contact*				
Product-Env-Stewards			Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			P	Phone - Representative*				Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Requester Item Number		Mfr Item Number		Mfr Item Name			Effective Date	Version	Version Manufacturing Site		7	Veight*	UOM	Unit Type
	RS1KFP			800V Fast Rect SOD123HE			2025-06-04		T	TSCBE		1.80026	mg	Each
	Process Informatio		orminal Desa	Alloy	STD-020 MSL I	Poting	Dook Deco	ogg Dody Ton	an a rotu = s	e Max Time at Peak	Tamparat	wa Numb	er of Reflow Cyc	alac
			Terminal Base Alloy J-STD CU Alloy 1		51D-020 MSL I	Kanng	Peak Process Body Te 260		nperature	30			er of Kerlow Cyc	cies
•	n (Sn) - annealed	C	U Alloy	1			200			30	second	ds 3		
omments	ima at neak tampat	a dunina1	domina ia 10-2	O seconds										
	ime at peak temperature													
: more informatio	on regarding material co	omposition p	piease refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier are written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Te											
RoHS Declaration * 4 - Item(s	s) does not contain RoHS restricted substance	ces per the definition above except for selected exer	nptions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead). Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature R		,									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	1.3299	mg	Supplier	Iron (Fe)	7439-89-6		0.0013	mg
			Supplier	Copper (Cu)	7440-50-8		1.3282	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0004	mg
Die	2.0218	mg	Supplier	Silicon (Si)	7440-21-3		1.8196	mg
			В	Nickel (Ni)	7440-02-0		0.0131	mg
			Supplier	Gold (Au)	7440-57-5		0.003	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	0.186	mg
Die Attach Solder	0.41096	mg	Supplier	Silver (Ag)	7440-22-4		0.0103	mg
			A	Lead (Pb)	7439-92-1	7a	0.3801	mg
			Supplier	Tin (Sn)	7440-31-5		0.0205	mg
Lead Frame	12.3086	mg	Supplier	Iron (Fe)	7439-89-6		0.0123	mg
			Supplier	Copper (Cu)	7440-50-8		12.2926	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0037	mg
Mold Compound-Black	5.7288	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.5757	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0286	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		4.8953	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.2292	mg
Plating	2.0E-4	mg	Supplier	Tin (Sn)	7440-31-5		0.0002	mg